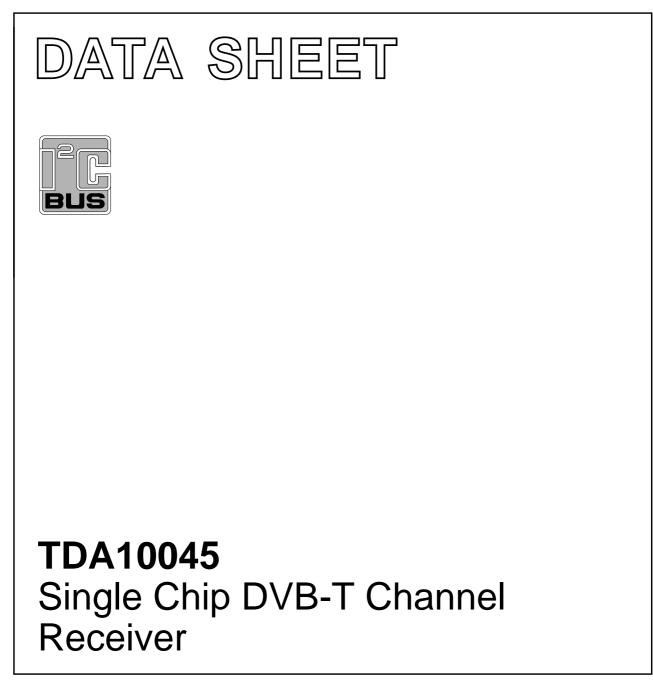
INTEGRATED CIRCUITS



Preliminary specification File under Integrated Circuits, IC02 2000 March 15



TDA10045

FEATURES

- 2K and 8K COFDM demodulator (Fully DVB-T compliant : ETS 300-744).
- All modes supported including hierarchical modes.
- Fully automatic transmission parameters detection.
- DSP based synchronization (upgradability).
- No extra-host software required.
- On chip 10-bit ADC.
- 2nd or 1st IF variable analog input.
- Only fundamental Crystal oscillator needed.
- Frequency offset estimator to speed up the scan.
- RF Tuner input power measurement
- Parallel or serial transport stream interface.
- On chip FEC decoder.
- BER measurement (before and after Viterbi decoder)
- SNR estimation
- TPS bits I2C readable (including spare ones)
- Channel frequency response output.
- Controllable dedicated I2C tuner bus (5V tolerant).
- 2 low frequency spare DAC. ($\Delta\Sigma$)
- Spare I/O.
- CMOS 0.2µm technology.

APPLICATIONS

- DVB-T fully compatible.
- Digital data transmission using COFDM modulations.

DESCRIPTION

The TDA10045 is a single chip channel receiver for 2K and 8K COFDM modulated signals based on the ETSI specification (ETSI 300 744). The device interfaces directly to an IF signal, which could be either first or second IF and integrates a 10-bit AD converter, a NCO and a PLL, simplifying external logic requirements and limiting system costs.

The TDA10045 performs all the COFDM demodulation tasks from IF signal to the MPEG2 transport stream. An internal DSP core manages the synchronization and the control of the demodulation process, and implements specially developed software for robustness against co and adjacent channel interferers, to deal with SFN echoes situations, and to help for a very fast scan of the bandwidth.

After base band conversion and FFT demodulation, the channel frequency response is estimated based on the scattered pilots, filtered in both time and frequency domains. This estimation is used as a correction on the signal, carrier by carrier. A common phase error and estimator is used to deal with the tuner phase noise.

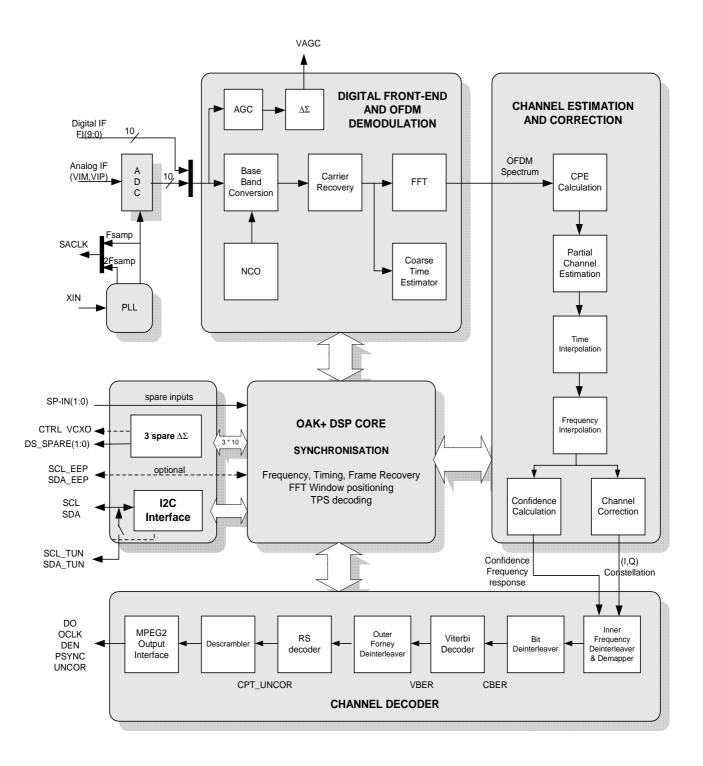
The FEC decoder is automatically synchronized thanks to the frame synchronization algorithm that uses the TPS information included in the modulation.

This device is controlled via an I2C bus (called master). The chip provides 2 switchable I2C bus derived from the master. A tuner I2C bus to be disconnected from the I2C master when not necessary and an Eeprom I2C bus. The DSP software code can be fed to the chip via the master I2C bus or via the dedicated Eeprom I2C bus.

Designed in 0.2 μ m CMOS technology and housed in a 100-pin MQFP package, the TDA10045 operates over the commercial temperature range.

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FIGURE 1 : INTERNAL BLOCK DIAGRAM



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INPUT - OUTPUT SIGNAL DESCRIPTION

SYMBOL	PIN NUMBER	TYPE	DESCRIPTION
CLOCK	AND RESET	SIGNA	LS
CLR#	14	I	Asynchronous reset signal, active low
XIN	80	I	Crystal oscillator input pin. Typically a fundamental XTAL oscillator is connected between XIN and XOUT.
XOUT	79	0	Crystal oscillator output pin.
SACLK	33	O (3.3V)	Sampling frequency output. This output clock can be fed to an external (10-bit) ADC as sampling clock. Depending on "Sel_Saclk" (Reg CONFADC), SACLK could also provide twice the sampling clock.
CTRL_VCXO	3	O (3.3V)	If not in NCO mode, control of an external sampling VCXO (after low-pass filtering)

DEMOI	DEMODULATOR SIGNALS			
FI[9:0]	34-35-36-37-38- 41-42-43-44-45	IO TRI	Input data from an external ADC, FI must be tied to ground when not used, positive notation (from 0 to 1023) or two's complement notation (from -512 to 511). In internal ADC mode, these outputs can be used to monitor extra demodulator output signal (constellation, frequency response).	
FFT_WIN	30	IO TRI	Output or input signal indicating the start of the active data; equals 1 during complex sample 0 of the active FFT block. Can be used to synchronize 2 chips.	
VAGC	4	O (3.3V)	output value from the Delta-Sigma Modulator, used to control a log-scaled amplifier (after analog filtering)	
FEL	49	0D (5V)	front end lock. FEL is an output drain output and therefore requires an external pull up resistor.	
IT	48	OD (5V)	Interrupt line. This output interrupt line can be configured by the I2C interface. See registers Itsel and Itstat. IT is an open drain output and therefore requires an external pull up resistor.	

FEC OU	FEC OUTPUTS			
DO[7:0]	67-68-69-72-73- 74-75-76	-	output data carrying the current sample of the current MPEG2 packet (188 bytes), delivered on the rising edge of OCLK by default. When the serial mode is selected, the output data is delivered by DO[0].	
OCLK	66	O (3.3V)	Output CLock. OCLK is the output clock for the parallel DO[7:0] outputs. (may be inverted, see POCLK and DISABLE_TS I2C registers)	
DEN	65	O (3.3V)	output data validation signal active high during the valid and regular data bytes (may be inverted, see PDEN and DISABLE_TS I2C registers).	
PSYNC	64	O (3.3V)	Pulse Synchro. This output signal goes high on a rising edge of OCLK when a synchro byte is provided, then goes low until the next synchro byte (may be inverted, see PPSYNC and DISABLE_TS I2C registers).	
UNCOR	63	O (3.3V)	RS error flag, active high on one RS packet if the RS decoder fails in correcting the errors (may be inverted, see PUNCOR and DISABLE_TS I2C registers).	

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ON-CH	ON-CHIP ADC SIGNALS			
VIM	92	I	Negative input to the A/D converter. This pin is DC biased to half supply through an internal resistor divider (2x20K resistors). In order to remain in the range of the ADC, the voltage difference between pins VIP and VIM should be between -0.5 and 0.5 volts (See SW I2C register).	
VIP	91	I	Positive input to the A/D converter. This pin is DC biased to half supply through an internal resistor divider (2x20K resistors). In order to remain in the range of the ADC, the voltage difference between pins VIP and VIM should be between -0.5 and 0.5 volts.	
VREFP	94	0	Positive voltage reference for the A/D converter. See SW I2C register for the output level.	
VREFM	93	0	Negative voltage reference for the A/D converter. See SW I2C register for the output level.	
VD1	100	I	Power supply input for the digital switching circuitry sensitive to the supply noise. The DC voltage should be 1,8V.	
VS1	99	I	Ground return for the digital switching circuitry.	
VD2	98	I	Power supply input for the analog clock drivers. The DC voltage should be 3.3V.	
VS2	97	I	Ground return for the analog clock drivers.	
VD3	95-90	Ι	Power supply input for the analog circuits. The DC voltage should be 3.3V.	
VS3	96-89		Ground return for analog circuits.	

I2C INTERFACES				
SCL	11	I	I2C master serial clock. Up to 700 kbit/s.	
SDA	12	I/O	I2C master serial data inout, open drain I/O pad.	
SADDR[1:0]	16-17	Ι	SADDR[1:0] are the 2 LSBs of the I2C address of the TDA10045. The MSBs are internally set to 00010. Therefore the complete I2C address of the TDA10045 is (MSB to LSB): 0,0,0,1,0,SADDR[1], SADDR[0]	
SCL_TUN	9	OD	Tuner I2C serial clock signal. This signal derived from the master SCL can be set to high impedance when no tuner acces needed. (See BP_I2C_TUN register) (open drain)	
SDA_TUN	10	I/O	Tuner I2C serial data signal. This signal derived from the master SDA can be set to high impedance when no tuner acces needed. (See BP_I2C_TUN register) (open drain)	
SCL_EEP	5	0	Extra I2C clock to download DSP code from an external EEPROM. (Optional mode). Can be connected to the master I2C Bus. (open drain)	
SDA_EEP	8	I/O	Extra I2C data bus to download DSP code from an external EEPROM. (Optional mode). Can be connected to the master I2C Bus. (open drain)	
EEPADDR	15	I	EEPRAD is the LSB of the I2C address of the EEPROM. The MSBs are internally set to 101000. Therefore the complete I2C address of the EEPROM is (MSB to LSB): 1,0,1,0,0,0, EEPADDR	

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DSP SIG	DSP SIGNALS		
DOWNLOAD	27	I	Processor control, Boot Mode If 0 the DSP downloads the software from an external eeprom on the dedicated I2C BUS (SDA_EEP, SCL_EEP). If 1 the software is downloaded in the I2C register CODE_IN from the host. In this case no need of external eeprom.
SP_IN[1:0]	28-29	I	Spare inputs
DS_SPARE_1	60	O (3.3V)	Spare delta-sigma output. Managed by the DSP to handle a low frequency DAC. (automatic first stage tuner AGC measurement for example).
DS_SPARE_2	59	O (3.3V)	Spare delta-sigma output. Managed by the DSP or by an I2C register to generate an analog level. (after a RC low-pass filter)

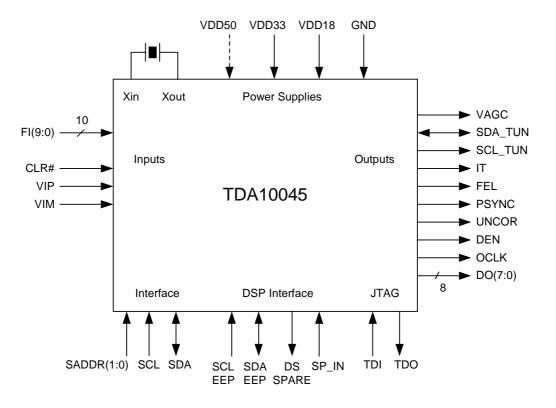
PLL SIGNALS				
PLLVCC	88	I	Power supply input for the analog circuits of the PLL module. (typ 3.3V)	
PLLGND	87	Ι	Ground return for the analog circuits of the PLL module.	
DGND	85	I	I Ground return for the digital circuits of the PLL module.	
DVCC	84	I	I Power supply input for the digital circuits of the PLL module. (typ 1.8V)	

BOUND	BOUNDARY SCAN			
TCK	55	I	clock signal for boundary-scan. Wired to GND (if not used)	
TDI	54	I	Input port for boundary-scan. Wired to GND (if not used)	
TMS	53	I	Mode programming signal for boundary-scan. Wired to GND (if not used)	
TRST	52	I	Asynchronous reset signal for boundary-scan. Wired to GND (if not used)	
TDO	56	O (3.3V)	Output port for boundary-scan. NC (if not used)	

POWEI	POWER SUPPLIES			
VSS	2-7-19-26-32-40- 47-58-62-71-78- 82	-	Ground level 0 V	
VDD50	25-46	VCC 5V	Positive Power Supply 5 V typical. If no need of 5V tolerant IO can be set to 3.3V (with caution).	
VDD33	1-6-31-61-77	VDD 3.3V	Positive Power Supply 3.3V typical	
VDD18	18-39-57-70-81	VDD 1.8V	Positive Power Supply 1.8V typical	

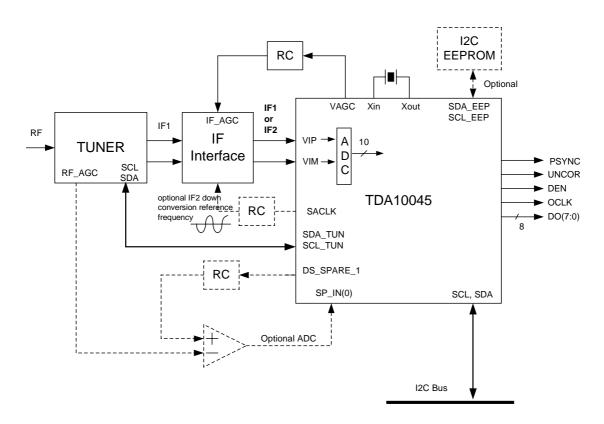
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FIGURE 2 : EXTERNAL BLOCK DIAGRAM



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FIGURE 3 : TYPICAL APPLICATION : DVB-T FRONT END RECEIVER



TUNER

- A RF tracking filter tracks the RF wanted frequency and suppresses the image.
- A first local AGC could be done at RF level, the AGC level information could be provided externaly and the chip
 offers facilities to measure this level thanks to the optional ADC (Rem: this measure is automaticaly made by the
 DSP, the host has just to read the result).
- A mixer oscillator and a PLL down-convert the RF signal to Intermediate Frequency IF1 typicaly 36.125 MHz
- SAW filters reject the adjacent analog channels power at IF1

IF INTERFACE

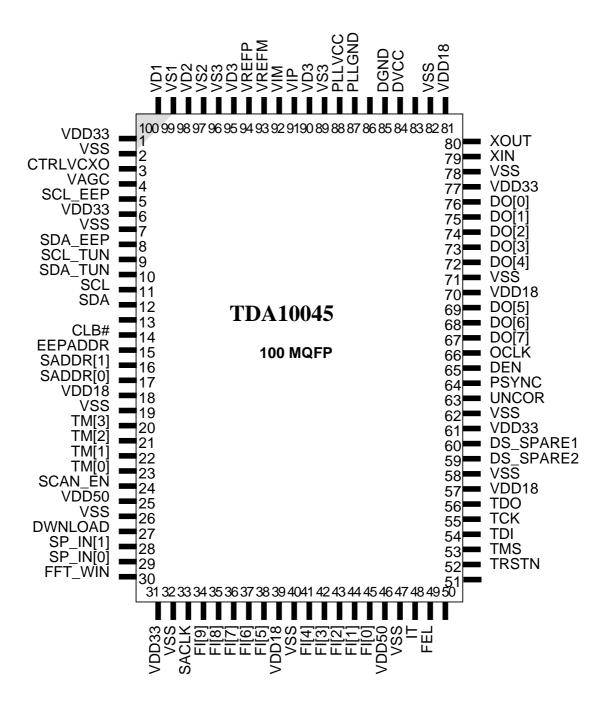
- It is either an analog IF amplifier when IF1 is sampled (digital down-conversion concept)
- Or an analog IF amplifier followed by a down-conversion from IF1 to IF2 at few MHz (ex :4.57 MHz)
- When this second solution is used, the ADC sampling clock could be used (after low-pass filtering) as reference clock for down-conversion (rem : twice the ADC sampling clock could also be provided see reg CONFADC).
- The IF amplifier is controlled by the digital AGC of the chip. A simple RC circuitry will filter the single-bit (ΔΣ modulated) AGC control (VAGC)
- The sampling clock could also be used to control an external ADC, then the input of the chip are digital (FI[9:0])

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- The chip is controlled by an I2C Bus and driven by an external low-cost crystal oscillator
- The software of the embedded DSP could be downloaded from the main I2C bus or from a dedicated I2C Bus connected to an external slave I2C Eeprom.
- An internal bidirectional switch allows to program the tuner through the chip and then switch off this link in order to avoid phase noise distortions due to I2C Bus traffic

TDA10045

FIGURE 4 : PIN DIAGRAM



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TABLE 1 : PIN DESCRIPTION

Pin	Pin Name	Direction
1	VDD33	Direction
2	VSS	-
2	CTRLVCXO	-
3		 0
2 3 4 5 6 7 8	VAGC	0
5	SCL_EEP	0
6	VDD33	-
7	VSS	-
	SDA_EEP	IOD
9	SCL_TUN	OD
10	SDA_TUN	IOD I
11	SCL	
12 13	SDA	IOD
13	-	-
14	CLB#	I
15	EEPADDR	I
16	SADDR[1]	I
17	SADDR[0]	I
18	VDD18	-
19	VSS	-
20	VSS	l ³
21	VSS	³
22	VSS	³
23	VSS	I ³
24	VSS	I ³
25	VDD50	-
26	VSS	-
27	DWNLOAD	-
28	SP_IN[1]	l
29	SP_IN[0]	l
30	FFT_WIN	IO
31	VDD33	
32	VSS	
33	SACLK	- - 0
34	FI[9]	10
34	FI[9]	IU

35	FI[8]	IO
36	FI[7]	IO
37	FI[6]	10
38	FI[5]	IO
39	VDD18	-
40	VDD18 VSS	-
41	FI[4]	10
42	FI[3]	IO
43	FI[2]	IO
44	FI[1]	10
45	FI[0]	10
46	FI[1] FI[0] VDD50	-
47	VSS	-
48	IT	OD
49	FEL	OD
50	-	-
51	-	-
52	TRSTN	-
53	TMS	Ι
54	TDI	I
55	TCK	I
56	TDO	0
57	VDD18	-
58	VSS	-
59	DS_SPARE2	- - 0 0
60	DS_SPARE1	0
61	VDD33	- - 0 0 0
62	VSS	-
63	UNCOR	0
64	PSYNC	0
65	DEN	0
66	OCLK	0
67	DO[7]	0
68	DO[6]	0
69	DO[5]	0 0
70	VDD18	-

71	VSS	-
72	DO[4]	0 0 0 0 0
73	DO[3]	0
74	DO[2]	0
73 74 75 76 77	DO[1]	0
76	DO[0]	0
77	VDD33	-
78	VDD33 VSS	-
79	XIN	I
80	XIN XOUT VDD18	0
81	VDD18	-
82	VSS	-
83	-	-
84	DVCC	-
85	DGND	-
86	-	-
87	PPLGND	-
88	PLLVCC	-
89	VS3 VD3	-
90	VD3	-
91	VIP VIM	-
92	VIM	-
93	VREFM	-
94	VREFP	-
95	VD3	-
96	VS3	-
97	VS2	-
98	VD2 VS1	-
99	VS1	-
100	VD1	-

Notes :

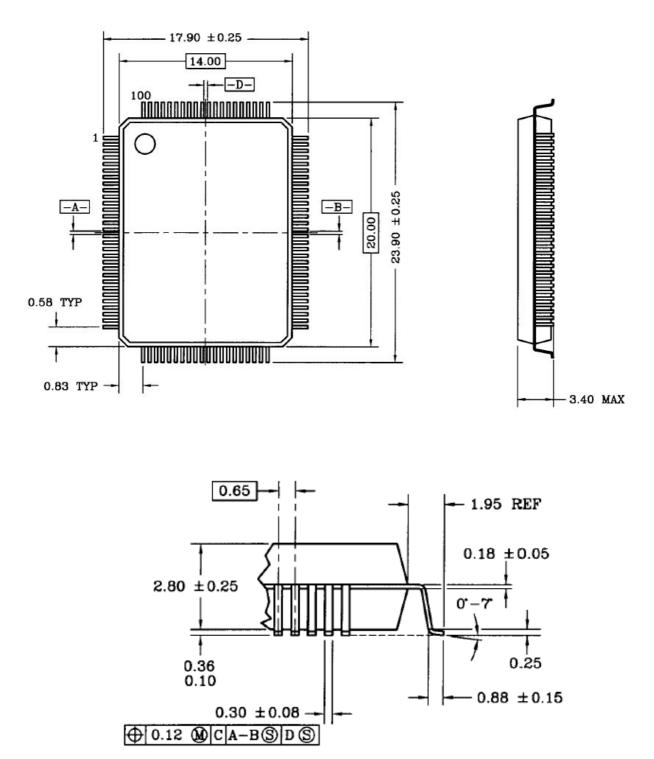
1.All inputs (I) are TTL, 5V tolerant inputs. (If VDD50 set to 5V).

2.OD are Open Drain 5V outputs, so they must be connected to a pull-up resistor to either VDD33 or VDD50

3. Foundry test IO, inputs must be connected to GND.

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PACKAGE INFORMATION



NOTE : Dimensions are in millimeters

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DATA SHEET STATUS	PRODUCT STATUS	DEFINITIONS ⁽¹⁾
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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Note

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